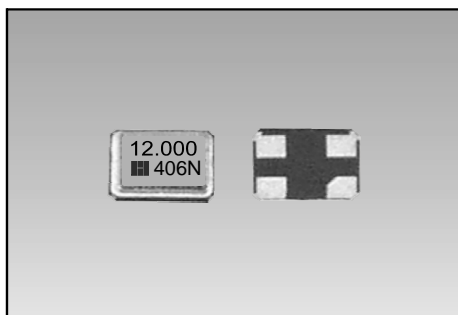


## • HCX-3SB Series 3.2X2.5X0.75 mm



### FEATURES

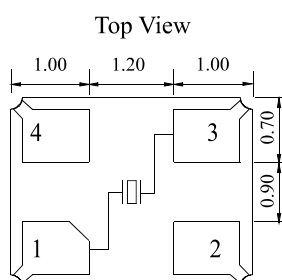
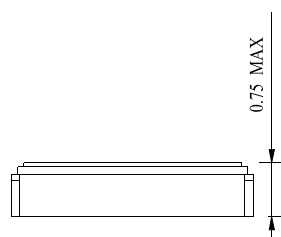
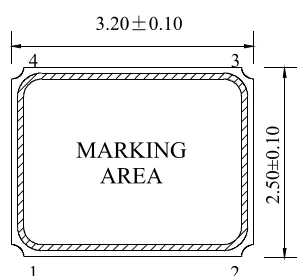
- Compact and thin (3.2X2.5X0.75mm max.)
- Frequency range of 10M to 54M with Fund
- Suitable application include telecommunications equipment, Short-range radio link modules,DVC,DSC PDA and Mobilephone.
- Excellent heat resistance and shock resistance.
- Products that are lead-free. These can meet the requirement of re-flow profiling using lead-free solder

### Electrical Specifications

Item	Type	HCX-3SB			
Frequency Range	F0	10 to 11.999MHz	12 to 19.999MHz	20 to 25.999MHz	26 to 54.000MHz
Mode of Vibration		Fundamental			
Load Capacitance	CL	6 to 20pF			
Frequency Tolerance	$\Delta F/F0$	$\pm 10\text{ppm}, \pm 15\text{ppm}, \pm 30\text{ppm}(\text{At } 25^\circ\text{C})$			
Equivalent Series Resistance	ESR	150 $\Omega$ max.	100 $\Omega$ max.	70 $\Omega$ max.	50 $\Omega$ max.
Temperature Stability	TC	$\pm 10\text{ppm}, \pm 15\text{ppm}, \pm 30\text{ppm}(\text{Refer to } 25^\circ\text{C})$			
Operating Temperature Range	T <sub>OPR</sub>	-20~+70 $^\circ\text{C}$ , -30~+85 $^\circ\text{C}$ Option			
Storage Temperature Range	T <sub>STG</sub>	-55~+125 $^\circ\text{C}$			
Shunt Capacitance	C0	3pF max.			
Insulator Resistance	IR	500M $\Omega$ min. (At 100VDC)			
Drive Level	DL	100 $\mu\text{W}$ (200 $\mu\text{W}$ max.)			
Aging	Fa	$\pm 2\text{ppm}$ max. (At 25 $^\circ\text{C}$ , First year)			
Packing Unit		3000pcs/reel			

*\*\*Please contact us for inquiries regarding other Specifications*

### Mechanical Dimensions(mm)



### Recommended Solder Pattern

